Amendments to the Specification

Please replace the paragraph at page 2, lines 5 through 16 with the following amended paragraph:

HBTs, however, can suffer from the disadvantage of having an abrupt discontinuity in the band alignment of the semiconductor material at the heterojunction can lead to a conduction band spike at the emitter-base interface of the HBT. The effect of this conduction band spike is to block electron transport out of the base into the collector. Thus, electron electrons stay in the base longer resulting in an increased level of recombination and a reduction of collector current gain (β_{dc}). Since, as discussed above, the turn-on voltage of heterojunction bipolar transistors is defined as the base-emitter voltage required to achieve a certain fixed collector current density, reducing the collector current gain effectively raise the turn-on voltage of the HBT. Consequently, further improvements in the fabrication of semiconductor materials of HBTs are necessary to lower the turn-on voltage, and thereby improve low voltage operation devices.

Please replace the paragraph at page 4, lines 6 through 11 with the following amended paragraph:

Another method of minimizing the conduction band spike is to include one or more transitional layers between the heterojunction. Transitional layers having low band gap set back layers, graded band gap layers, doping spikes or a combination [[of]] thereof can be used to minimize the conduction band spike. In addition, one or more lattice-matched layers can be present between the base and emitter or base and collector to reduce the lattice strain on the materials at the heterojunction.